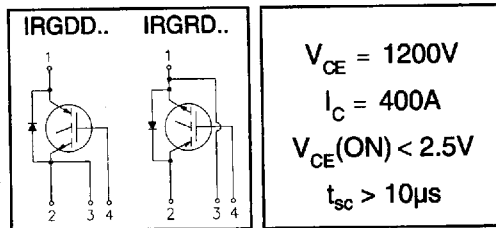


IRGDDN400M12 IRGRDN400M12

"SINGLE SWITCH" IGBT DOUBLE INT-A-PAK

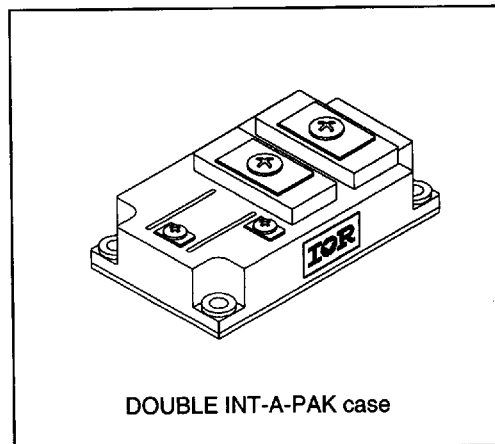
Low conduction loss IGBT

- Rugged Design
- Simple gate-drive
- Switching-Loss Rating includes all "tail" losses
- Short circuit rated



Description

IR's advanced IGBT technology is the key to this line of DOUBLE INT-A-PAK Power Modules. The efficient geometry and unique processing of the IGBT allow higher current densities than comparable bipolar power module transistors, while at the same time requiring the simpler gate-drive of the familiar power MOSFET. This superior technology has now been coupled to state of the art assembly techniques to produce a higher current module that is highly suited to power applications such as motor drives, uninterruptible power supplies, welding and power factor correction.



Absolute Maximum Ratings

Parameter	Description	Value	Units
V_{CES}	Continuous collector to emitter voltage	1200	V
$I_C @ T_C = 25^\circ C$	Maximum continuous collector current	400	A
R_{thJC}	Thermal resistance junction to case	0.045	$^\circ C/W$
$E_{is} @ T_J = 125^\circ C$	Total switching energy, $R_G = 4.7\Omega$, $V_{CC} = 600V$, $I_C = 400A$	0.55	mJ/A
I_{LM}	Peak switching current	800	A
I_{FM}	Peak diode forward current (1)	800	
V_{GE}	Gate to emitter voltage	± 20	V
V_{ISOL}	RMS isolation voltage, any terminal to case, $t = 1 \text{ min}$	2500	
$P_D @ T_C = 25^\circ C$	Power dissipation	2770	W
T_J	Operating junction temperature range	-40 to 150	$^\circ C$
T_{STG}	Storage temperature range	-40 to 125	

(1) Duration limited by max junction temperature.

Target Data

IRGDDN400M12 IRGRDN400M12



Electrical Characteristics - $T_J = 25^\circ\text{C}$, unless otherwise stated

Parameter	Description	Min	Typ	Max	Units	Test Conditions
BV_{CES}	Collector-to-emitter breakdown voltage	1200	—	—	V	$V_{GE} = 0V, I_C = 12mA$
$V_{CE(ON)}$	Collector-to-emitter voltage	—	2.3	2.7		$V_{GE} = 15V, I_C = 400A$
V_{FM}	Diode forward voltage - maximum	—	1.8	—		$V_{GE} = 15V, I_C = 300A, T_J = 150^\circ\text{C}$
		—	3.2	3.4		$I_F = 400A, V_{GE} = 0V$
V_{GEth}	Gate threshold voltage	—	2.6	—		$I_F = 400A, V_{GE} = 0V, T_J = 150^\circ\text{C}$
		3.0	—	5.5	$I_C = 4mA$	
ΔV_{GEth}	Threshold voltage temperature coefficient	—	-11	—	mV/ $^\circ\text{C}$	$V_{CE} = V_{GE}, I_C = 4mA$
g_{fe}	Forward transconductance	140	—	280	S(T_J)	$V_{CE} = 25V, I_C = 400A$
I_{CES}	Collector-to-emitter leakage current	—	—	12	mA	$V_{GE} = 0V, V_{CE} = 1200V$
		—	—	120		$V_{GE} = 0V, V_{CE} = 1200V, T_J = 150^\circ\text{C}$
I_{GES}	Gate-to-emitter leakage current	—	—	± 12	μA	$V_{GE} = \pm 20V$

Dynamic Characteristics - $T_J = 125^\circ\text{C}$

Parameter	Description	Min	Typ	Max	Units	Test Conditions
E_{on}	Turn-on switching energy	—	0.19	—	mJ/A	$R_G = 15\Omega, V_{CC} = 600V$
$E_{off} (1)$	Turn-off switching energy	—	0.34	—		$I_C = 400A, L_S = 100nH$
$E_{ts} (1)$	Total switching energy	—	—	0.60		$V_{GE} = \pm 15V$
$t_{d(on)}$	Turn-on delay time	—	400	550	ns	$R_G = 15\Omega, V_{CC} = 600V$
t_r	Rise time	—	600	800		$I_C = 400A$
$t_{d(off)}$	Turn-off delay time	—	550	650		$V_{GE} = \pm 15V$
t_f	Fall time	—	650	—		Resistive Load, $T_J = 25^\circ\text{C}$
I_{rr}	Diode peak recovery current	—	130	—		A
t_{rr}	Diode recovery time	—	220	—	ns	$I_C = 400A$
Q_{rr}	Diode recovery charge	—	16.5	—	μC	$V_{GE} = \pm 15V$
Q_{ge}	Gate-to-emitter charge (turn-on)	440	—	1000	nC	$V_{CC} = 600V$
Q_{gc}	Gate-to-collector charge (turn-on)	600	—	1900		$I_C = 400A$
Q_g	Total gate charge (turn-on)	3700	—	4500		$V_{GE} = 15V$
C_{iss}	Input capacitance	63000	—	66000	pF	$V_{GE} = 0V$
C_{oss}	Output capacitance	3900	—	6600		$V_{CC} = 30V$
C_{res}	Reverse transfer capacitance	3900	—	6600		$f = 1MHz$
t_{sc}	Short circuit withstand time	10	—	—	μs	$V_{CC} = 720V, V_{GE} = \pm 15V$ Min. $R_G = 15\Omega, V_{CEP} = 1000V$

(1) Includes tail losses

Thermal and Mechanical Characteristics

Parameter	Description	Typ	Max	Units
R_{thJC} (IGBT)	Thermal resistance, junction to case, each IGBT	—	0.047	$^\circ\text{C/W}$
R_{thJC} (Diode)	Thermal resistance, junction to case, each diode	—	0.052	
R_{thCS} (Module)	Thermal resistance, case to sink	0.023	0.050	
Wt	Weight of module	242	—	g

Refer to Section D - page D-18 for Package Outline 13 - Double INT-A-PAK Single Switch